

**--Abstract of the Disclosure**

Provided is a conductive paste which can have high conductivity even if the sintering temperature is 500° C or less, and which does not cause an interference pattern or crack on a substrate even if a thick film thereof is formed on the substrate. The conductive paste comprises main components including a metal powder, a glass frit, and an organic vehicle. The metal powder is composed of spherical particles (A) having an average primary-particle diameter of 0.1 to 1  $\mu\text{m}$  and spherical particles (B) having an average primary-particle diameter of 50 nm or less, and the content of spherical particles (A) ranges from 50 to 99 wt% and the content of spherical particles (B) ranges from 1 to 50 wt%. The content of the glass frit ranges from 0.1 wt% to 15 wt% to the total amount of the glass frit and the metal powder. Preferably, the glass frit does not contain lead and has a working point of 500° C[[.]] or less, and the average particle diameter thereof is 2  $\mu\text{m}$  or less. The present invention can widely be applied to print on a substrate and sinter so as to form an electric circuit on the substrate.--